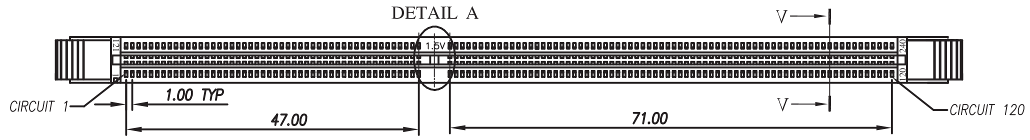
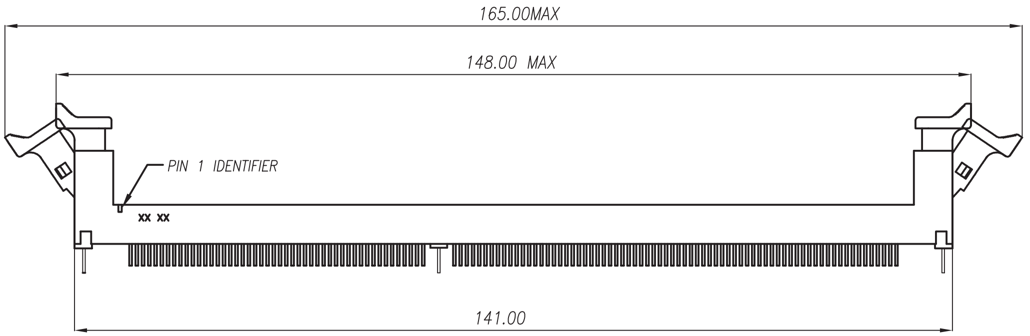
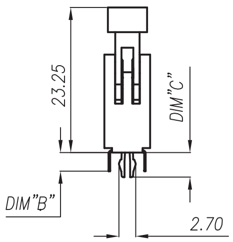
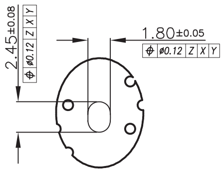
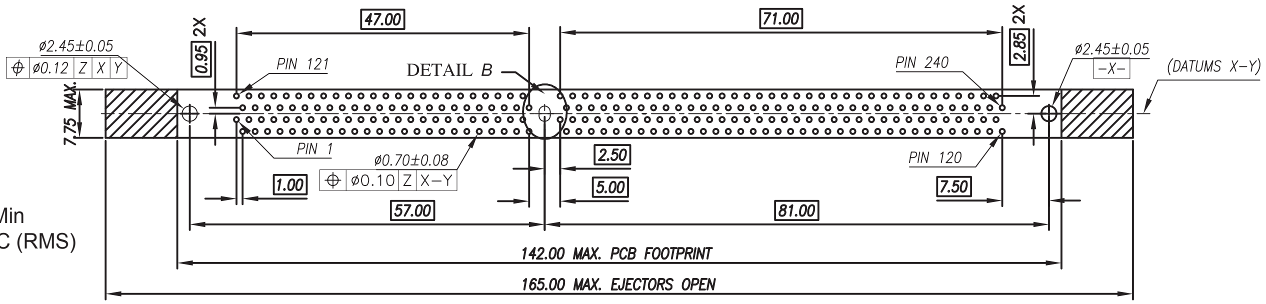


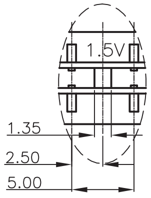






DETAIL B





DETAIL A (2:1)

ELECTRICAL:

CURRENT RATING: 1.0 Amps/pin
VOLTAGE RATING: 30 Volts AC (RMS)/DC
CONTACT RESISTANCE: 30 Milliohms Max
INSULATION RESISTANCE: 1000 Megaohms Min
DIELECTRIC WITHSTAND VOLTAGE: 500 V AC (RMS) at 60 Seconds hold time
OPERATING TEMPERANCE: -10°C to +85°C

MATERIAL:

RETENTION CLIP: BRASS
INSULATOR: Nylon 4/6, UL94V-O
LATCHES: Nylon 46 UL94V-O
CONTACTS: Phosphor Bronze
PLATING: Gold over 50u" (Min) Nickel in Contact Area; 100u" (Min) Nickel on Solder Tail

MECHANICAL:

MODULE INSERTION FORCE: 10 Kgf Max
DURABILITY: 25 Cycles Min

HOW TO ORDER:

B 0 3 7 - 2 4 0 X - 0 2 0 - X Z

NUMBER OF CONTACTS:
240

PC TAIL / CLIP DIMENSION

	Dim "B"	Dim "C"
5	2.67mm	2.55
6	3.18mm	2.70

DEFINITION:
0 - STRAIGHT

VOLTAGE:
2 - 1.5 Volts

SELECTIVE GOLD PLATING:
A- Gold Flash/100μ" Tin
0 - 10μ" Gold/100μ" Tin
1 - 15μ" Gold/100μ" Tin
2 - 30μ" Gold/100μ" Tin

ROHS COMPLIANT

Rev	Description	Drawn	Checked	Approved	Date
0	Issued	MDH	S.M.	S.M.	06/15/09

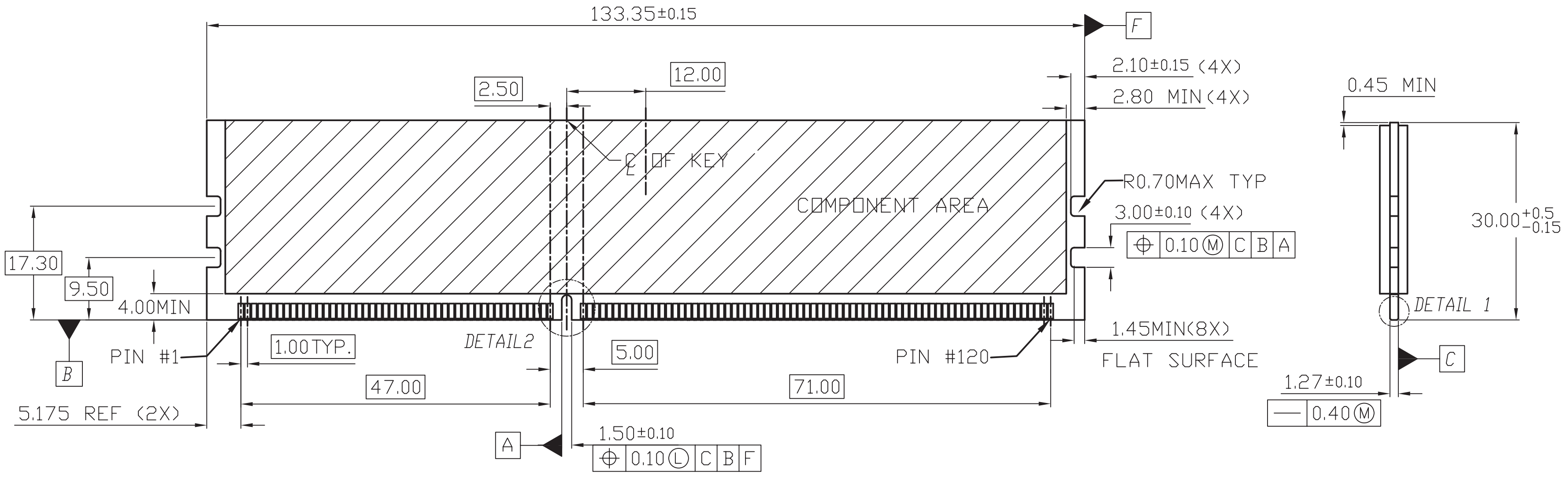
SCALE:n/a

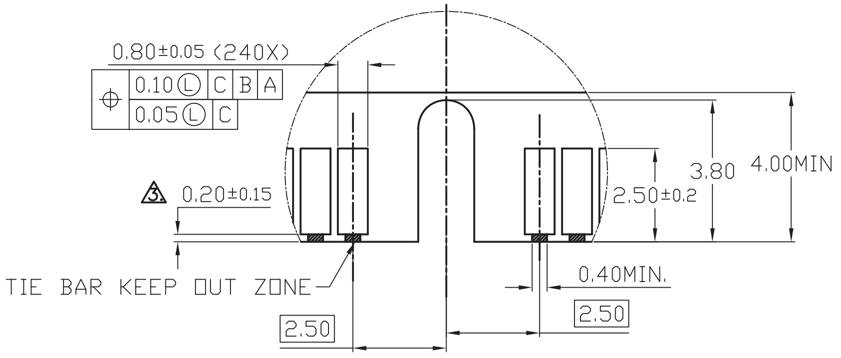
TOL. DEC. .X +/- 0.38 .XX +/- 0.25 .XXX +/- 0.08 ANGLE +/- 3° UNIT: mm

SMP TECHNOLOGY, INC.

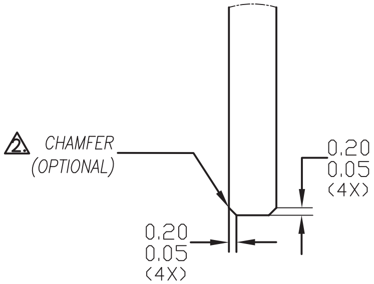
DDR III DIMM Socket, Vertical, 240 Position, Thru Hole, 1.5 Volt

P/N: B037-240X-020-XZ





DETAIL 2



DETAIL 1

NOTES:

1.RECOMMENDED PLATING FOR CONTACT PADS:

PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN.
OVER 2.00 MICROMETERS NICKEL
ALTERNATIVE: 0.05~0.75 MICROMETERS GOLD PLATING
OVER 2.00 MICROMETERS NICKEL MUST USE AN ELECTRONIC
CONTACT GRADE CORROSIVE BARRIER LUBRICANT

2 CHAMFER IS OPTIONAL AND IS NOT TO HIT GOLD PADS

3 LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS.

Rev	Description	Drawn	Checked	Approved	Date
0	Issued	MDH	S.M.	S.M.	06/15/09

SMP TECHNOLOGY, INC.

DDR III DIMM Socket, Vertical, 240 Position, Thru Hole, 1.5 Volt

SCALE:n/a

TOL. DEC. .X +/- 0.38 .XX +/- 0.25 .XXX +/- 0.08 ANGLE +/- 3° UNIT: mm

P/N: B037-240X-020-XZ